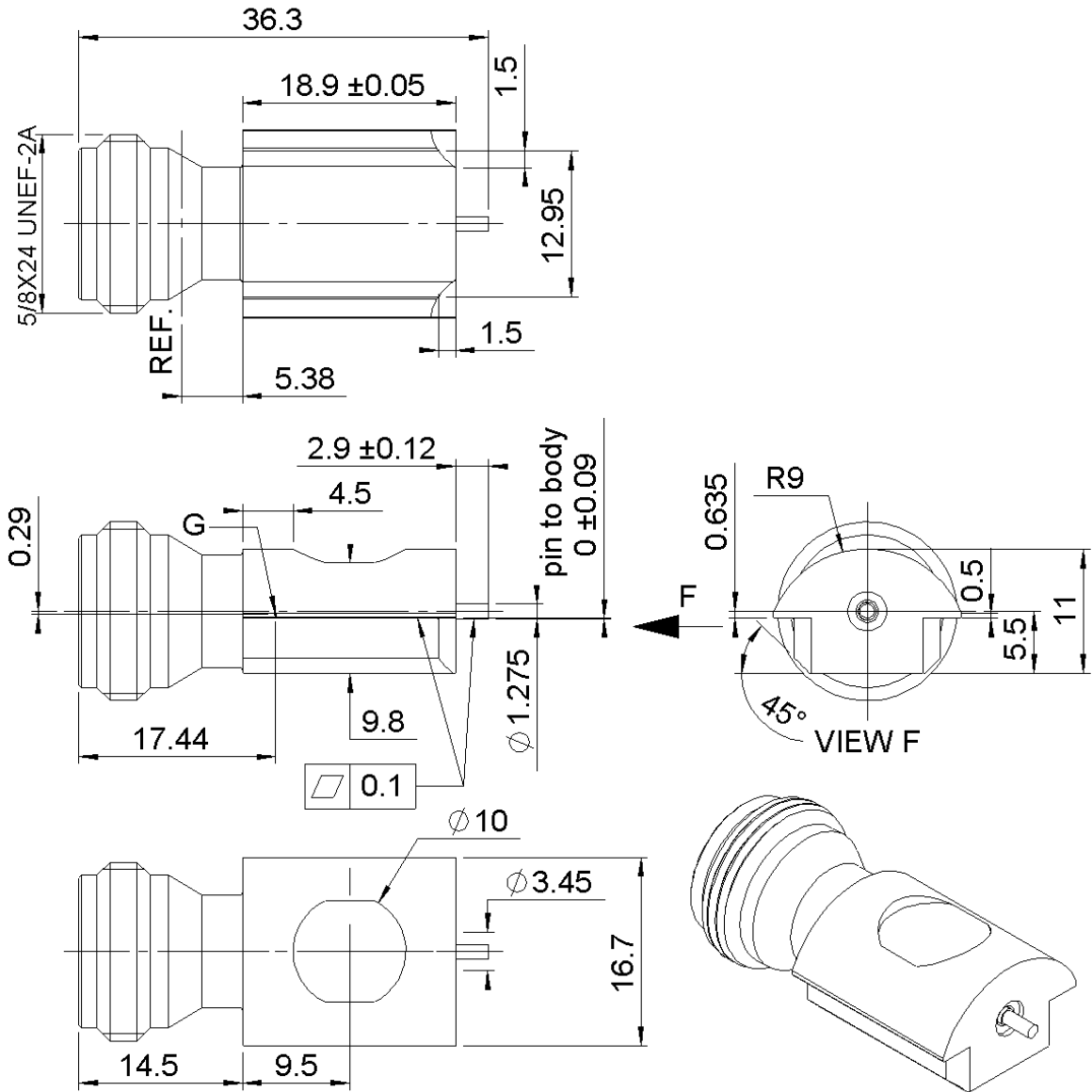


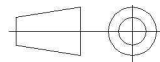
**EDGE CARD FEMALE RECEPTACLE**

**R161.427.223**

Series : N



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
BODY	BRASS	NPGR
CENTER CONTACT	BERYLLIUM COPPER	NPGR
OUTER CONTACT	-	-
INSULATOR	PTFE	-
GASKET	-	-
OTHERS PARTS	-	-
.	.	.
.	.	.

Issue : 0749 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



**EDGE CARD FEMALE RECEPTACLE**

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Series : N

**PACKAGING**

**SPECIFICATION**

Standard	Unit	Other
<b>20</b>	<b>'W' option</b>	<b>Contact us</b>

**ELECTRICAL CHARACTERISTICS**

**ENVIRONMENTAL**

Impedance	<b>50</b>	$\Omega$
Frequency	<b>0-11</b>	GHz
VSWR	<b>1.2 + 0,0000</b>	x F(GHz) Maxi
Insertion loss	<b>0.15</b>	$\sqrt{F}$ (GHz) dB Maxi
RF leakage	- ( <b>NA</b> )	- F(GHz)) dB Maxi
Voltage rating	<b>1400</b>	Veff Maxi
Dielectric withstanding voltage	<b>1500</b>	Veff mini
Insulation resistance	<b>5000</b>	M $\Omega$ mini

Operating temperature	<b>-55/+155</b>	$^{\circ}$ C
Hermetic seal	<b>NA</b>	Atm.cm3/s
Panel leakage	<b>NA</b>	

**OTHER CHARACTERISTICS**

Assembly instruction **NA**

Others :  
0-3GHz

**MECHANICAL CHARACTERISTICS**

Center contact retention		
Axial force – Mating end	<b>27</b>	N mini
Axial force – Opposite end	<b>20</b>	N mini
Torque	<b>NA</b>	N.cm mini
Recommended torque		
Mating	<b>NA</b>	N.cm
Panel nut	<b>NA</b>	N.cm
Mating life	<b>500</b>	Cycles mini
Weight	<b>28,7000</b>	g

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**EDGE CARD FEMALE RECEPTACLE**

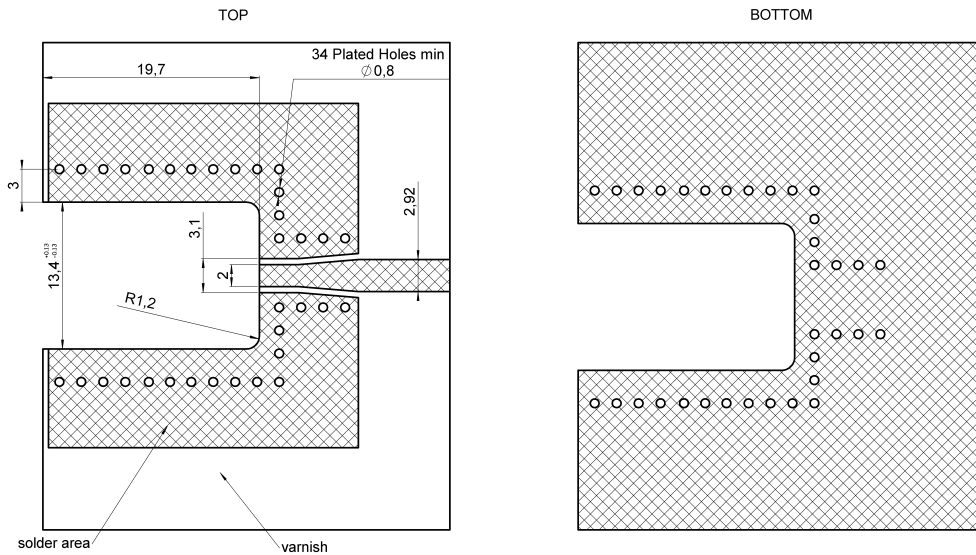
**R161.427.223**

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**N SERIES - INFORMATIONS**

Strip line Thickness of PCB : 1.6mm

The material of PCB is FR4 . (Er = 4.6) .



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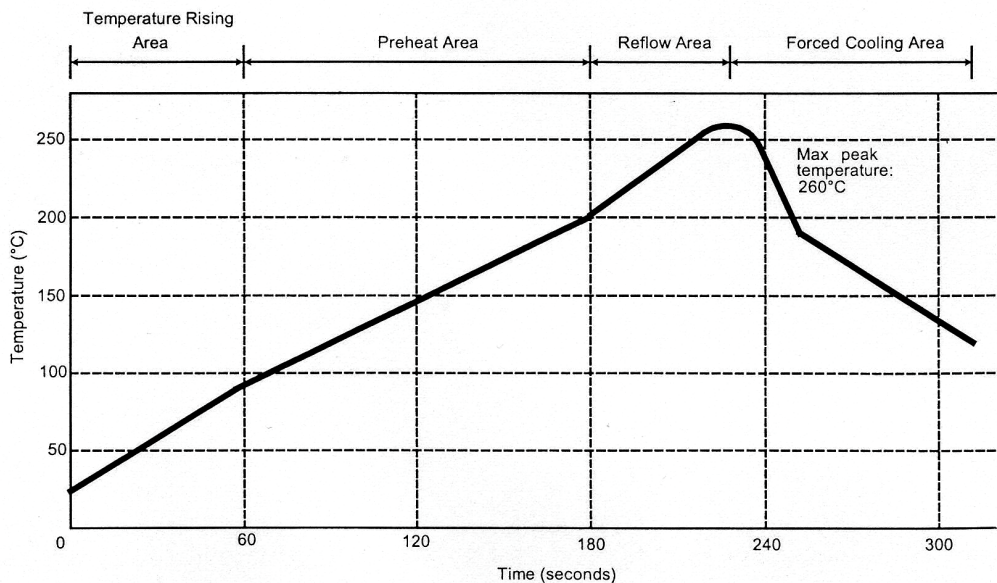
**EDGE CARD FEMALE RECEPTACLE**

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**SOLDER PROCEDURE**

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.  
We advise a thickness of 150 microns ( 5.850 microinch ). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.  
Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.  
Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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